



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: DSNO-14QHSI980

Date:
March 23, 2026

Qualification of MMT as an additional assembly site for 25AA128-I/MF, 25AA128T-I/MF, 25AA256-I/MF, 25AA256T-I/MF, 25AA640A-E/MF, 25AA640A-I/MF, 25AA640AT-E/MF, 25LC128-E/MF, 25LC128-I/MF, 25LC128T-E/MF, 25LC128T-I/MF, 25LC256-E/MF, 25LC256-I/MF, 25LC256T-E/MF, 25LC256T-I/MF, 25LC640A-E/MF and 25LC640A-I/MF catalog part numbers (CPN) available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification.



MICROCHIP Package Qualification Report

Purpose: Qualification of MMT as an additional assembly site for 25AA128-I/MF, 25AA128T-I/MF, 25AA256-I/MF, 25AA256T-I/MF, 25AA640A-E/MF, 25AA640A-I/MF, 25AA640AT-E/MF, 25LC128-E/MF, 25LC128-I/MF, 25LC128T-E/MF, 25LC128T-I/MF, 25LC256-E/MF, 25LC256-I/MF, 25LC256T-E/MF, 25LC256T-I/MF, 25LC640A-E/MF and 25LC640A-I/MF catalog part numbers (CPN) available in 8L DFN-S (6x5x0.9mm) package. This is a Q006 Grade 1 qualification.

CCB No.: 7870

Misc.	Assembly site	MMT
	BD Number	BD-003829-01
	MP Code (MPC)	358A24A6XA00
	Part Number (CPN)	25LC256-E/MF
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	60
Lead-Frame	Paddle size	173x173
	Material	C194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening LF
	Process	Etched LF
	Lead-lock	Locking hole
	Part Number	10100879
	Lead Plating	Matte Tin
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519 (PFAS free)
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	DFN-S
	Pin/Ball Count	8
	PKG width/size	6x5x0.9mm



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Package Qualification Report

Manufacturing Information:

MPC	Wafer Lot No.	Package
358A24A6XA00	MMT-263500383.000	8L DFN-S
358A24A6XA00	MMT-263501053.000	8L DFN-S
358A24A6XA00	MMT-263501070.000	8L DFN-S

Conclusion:

Qualification of 358A2 mask / 25LC256-E/MF product / 0.8 mil CuPdAu wire in 8L DFN-S 6x5x0.9mm (A6X) package at MMT site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		



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Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 500 hours		
Required Sample Size	45 units each lot / 3 lots; WBS and IPA		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 1000 hours		
Required Sample Size	45 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		



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Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 1000 Cycles		
Required Sample Size	77 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
CSAM Results (Fail / Pass)	0/22	0/22	0/22
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 2000 Cycles		
Required Sample Size	77 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		



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Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 192 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
IPA Decapsulation	0/1	0/1	0/1
Electrical Test Tester: NEXTEST_PT	25°C, 85°C, and 125°C		
Result	Passed		



MICROCHIP Package Qualification Report

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots		
Lot ID	R2501528-1 MMT-263500383.000	R2501528-2 MMT-263501053.000	R2501528-3 MMT-263501070.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
IPA Decapsulation	0/5	0/5	0/5
Electrical Test Tester: NEXTEST_PT	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result	Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30
Result	Passed

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed